Title (en)

SEMICONDUCTOR CHIP HAVING FLIP-CHIP CONTACTS AND METHOD FOR PRODUCING THE SAME

Title (de)

HALBLEITERCHIP MIT FLIP-CHIP-KONTAKTEN UND VERFAHREN ZUR HERSTELLUNG DESSELBEN

Title (fr)

PUCE A SEMI-CONDUCTEUR PRESENTANT DES CONTACTS DE PUCE RETOURNEE ET PROCEDE POUR PRODUIRE CETTE PUCE

Publication

EP 1680812 A2 20060719 (DE)

Application

EP 04802671 A 20041103

Priority

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Abstract (en)

[origin: WO2005045931A2] The invention relates to a semiconductor chip (1) having flip-chip contacts (2), whereby the flip-chip contacts (2) are placed on contact surfaces (3) of the active top side (4) of the semiconductor chip (1). The contact surfaces (3) are surrounded by a passivation layer (5) that covers the active top side (4) while leaving the contact surfaces (3) exposed. The passivation layer (5) comprises thickenings (6) that encircle the contact surfaces (3). A semiconductor layer (1) of this type with thickenings (6) encircling the contact surfaces (3) is protected from delamination when packing the semiconductor chip (1) to form a semiconductor component.

IPC 1-7

H01L 23/485

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2005045931A2

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